

# High Current, Low-Profile Power Inductors

## FLAT-PAC™ FP0705 Series



### Applications

- Portable electronics
- Servers and workstations
- Data networking and storage systems
- Notebook and desktop computers
- Graphics cards and battery power systems
- Multi-phase regulators
- Voltage Regulator Module (VRM)
- DCR sensing

### Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (Range is application specific)
- Solder reflow temperature: J-STD-020D compliant

### Packaging

- Supplied in tape-and-reel packaging, 950 parts per reel, 13" dia. reel

### Description

- 125°C maximum total temperature operation
- 7.0 x 7.0 x 4.95mm surface mount package
- Ferrite core material, High current carrying capacity
- Low core losses
- Controlled DCR tolerance for sensing circuits
- Inductance range from 72nH to 220nH
- Current range from 20 to 65 Amps, frequency range up to 2MHz
- RoHS compliant

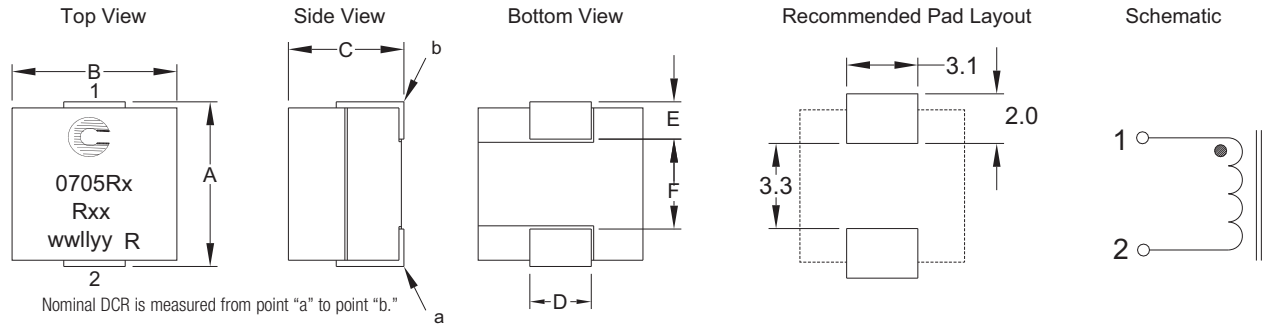
### Product Specifications

Part Number	OCL <sup>1</sup> ± 10% (nH)	FLL <sup>2</sup> Min. (nH)	I <sub>rms</sub> <sup>3</sup> (Amps)	I <sub>sat</sub> <sup>14</sup> @ 25°C (Amps)	I <sub>sat</sub> <sup>25</sup> @ 125°C (Amps)	DCR (mOhm)@20°C	K-factor <sup>6</sup>
<b>R1 Version</b>							
FP0705R1-R07-R	72	51	43	65	50	0.25 ± 10%	826
FP0705R1-R10-R	105	75		44	36		826
FP0705R1-R12-R	120	86		37	30		826
FP0705R1-R15-R	150	108		30	24		826
FP0705R1-R18-R	180	130		25	20		826
FP0705R1-R22-R	220	158		20	16		826
<b>R2 Version</b>							
FP0705R2-R07-R	72	51	38	65	50	0.32 ± 9.4%	826
FP0705R2-R10-R	105	75		44	36		826
FP0705R2-R12-R	120	86		37	30		826
FP0705R2-R15-R	150	108		30	24		826
FP0705R2-R18-R	180	130		25	20		826
FP0705R2-R22-R	220	158		20	16		826
<b>R3 Version</b>							
FP0705R3-R07-R	72	51	32	65	50	0.46 ± 6.5%	826
FP0705R3-R10-R	105	75		44	36		826
FP0705R3-R12-R	120	86		37	30		826
FP0705R3-R15-R	150	108		30	24		826
FP0705R3-R18-R	180	130		25	20		826
FP0705R3-R22-R	220	158		20	16		826

1 Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10V<sub>rms</sub>, 0.0A<sub>dc</sub>  
 2 Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, I<sub>sat</sub><sup>1</sup>  
 3 I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB pad layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended the part temperature not exceed 125°C under worst case operating conditions verified in the end application.

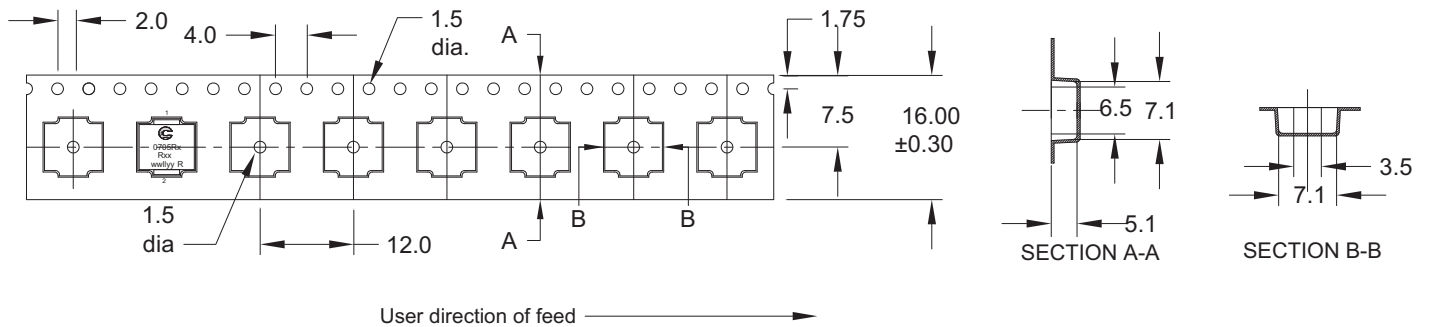
4 I<sub>sat</sub><sup>1</sup>: Peak current for approximately 20% rolloff at +25°C.  
 5 I<sub>sat</sub><sup>2</sup>: Peak current for approximately 20% rolloff at +125°C.  
 6 K-factor: Used to determine B<sub>p-p</sub> for core loss (see graph). B<sub>p-p</sub> = K \* L \* ΔI \* 10<sup>-3</sup>, B<sub>p-p</sub>: (Gauss), K: (K-factor from table), L: (inductance in nH), ΔI (peak-to-peak ripple current in amps).  
 7 Part Number Definition: FP0705Rx-Rxx-R  
 • FP0705 = Product code and size  
 • Rx is the DCR indicator  
 • Rxx= Inductance value in μH, R = decimal point  
 • "-R" suffix = RoHS compliant

**Dimensions - mm**     $A = 7.0 \text{ Max.}$      $B = 7.0 \text{ Max.}$      $C = 4.95 \text{ Max.}$      $D = 2.45 \pm 0.2$      $E = 1.52 \pm 0.2$      $F = 3.5 \text{ Typ.}$



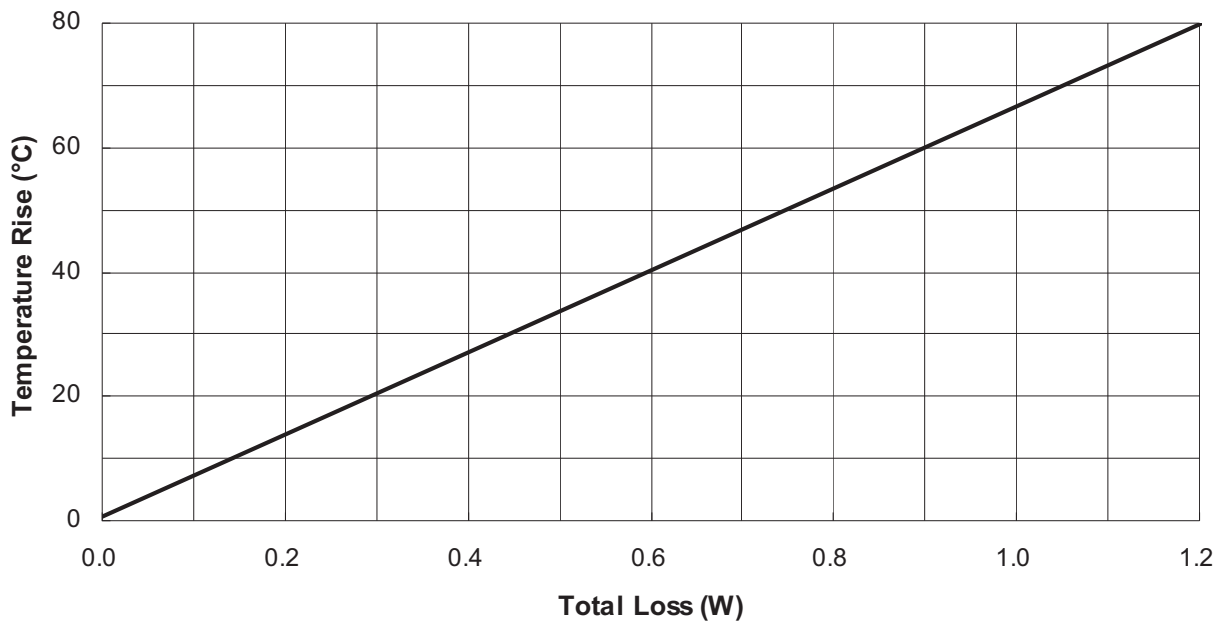
Part Marking: Coiltronics Logo    0705Rx (Rx = DCR indicator)    Rxx = inductance value in  $\mu\text{H}$  (R = decimal point)    wwllyy = date code    R = revision level

### Packaging Information - mm



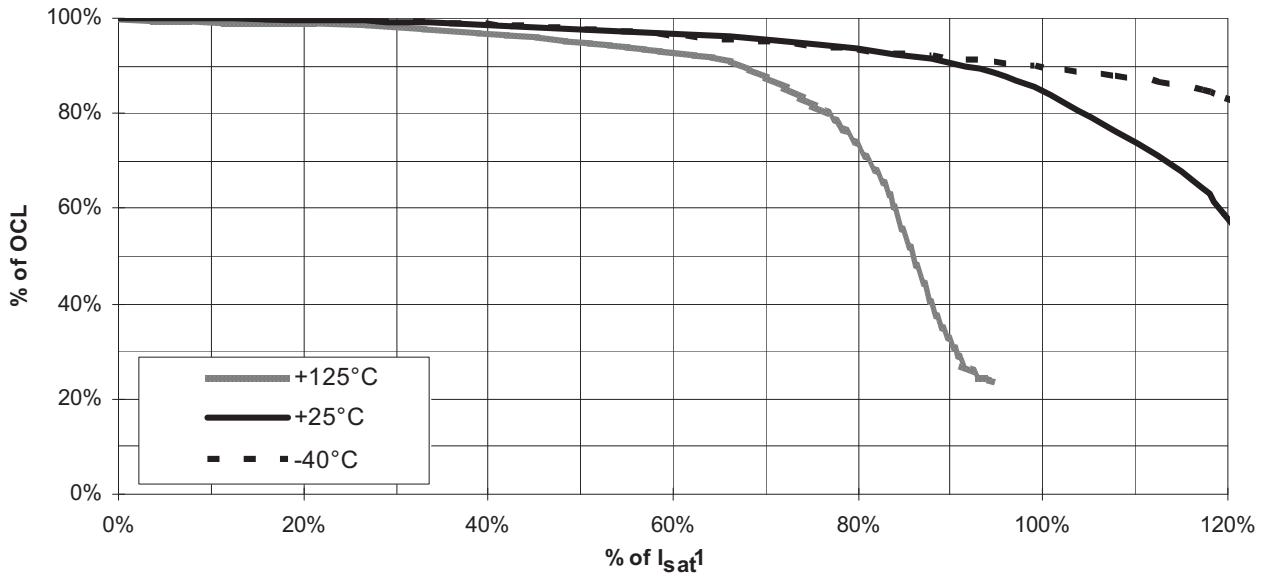
Supplied in tape-and-reel packaging, 950 parts per reel, 13" diameter reel.

### Temperature Rise vs. Total Loss



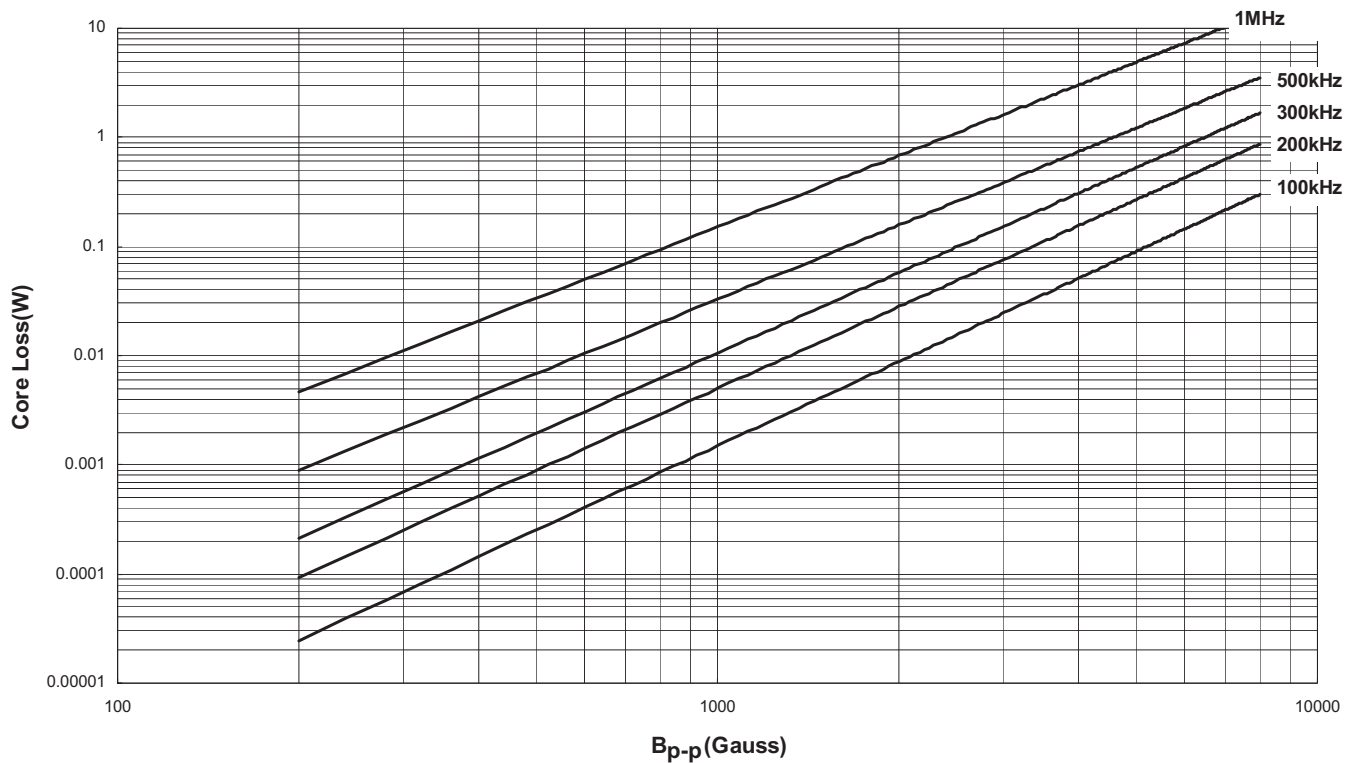
## Inductance Characteristics

### OCL vs. $I_{sat}^1$



## Core Loss

### Core Loss vs. $B_{p-p}$



## Solder Reflow Profile

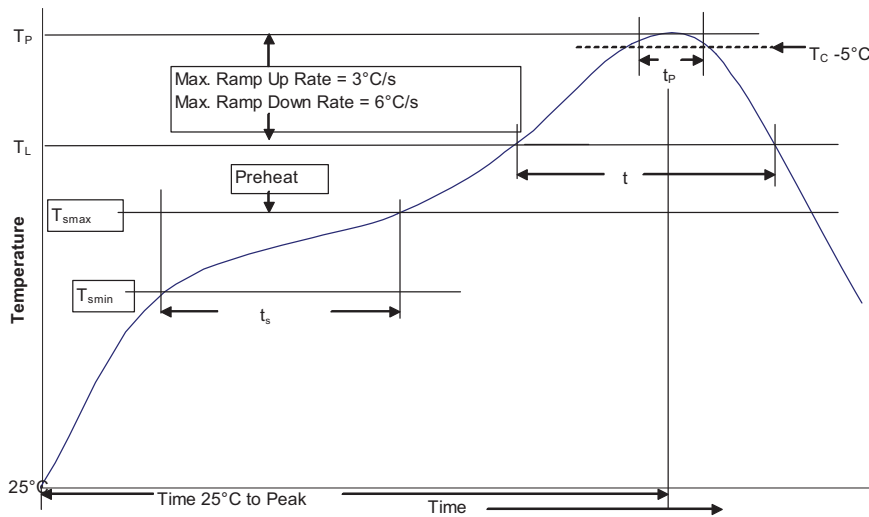


Table 1 - Standard SnPb Solder ( $T_c$ )

Package Thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ $\geq 350$
<2.5mm	235°C	220°C
$\geq 2.5\text{mm}$	220°C	220°C

Table 2 - Lead (Pb) Free Solder ( $T_c$ )

Package Thickness	Volume $\text{mm}^3$ <350	Volume $\text{mm}^3$ 350 - 2000	Volume $\text{mm}^3$ >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. ( $T_{smin}$ )	100°C
	• Temperature max. ( $T_{smax}$ )	150°C
	• Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 Seconds
Average ramp up rate $T_{smax}$ to $T_p$	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature ( $T_L$ )	183°C	217°C
Time at liquidous ( $t_L$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_c$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

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